

(0.635 mm) .025"

QTS SERIES

# HIGH-SPEED GROUND PLANE HEADER

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?QTS](http://www.samtec.com?QTS)

**Insulator Material:**

Liquid Crystal Polymer

**Contact Material:**

Phosphor Bronze

**Plating:**

Au or Sn over 50 μm (1.27 μm) Ni

**Current Rating:**

Contact: 1.8 A per pin (2 pins powered)

Ground Plane: 23.1 A per ground plane (1 ground plane powered)

**Operating Temp:**

-55 °C to +125 °C

**Voltage Rating:**

285 VAC

**Max Cycles:**

100

**RoHS Compliant:**

Yes

**Board Mates:**

QSS

**Cable Mates:**

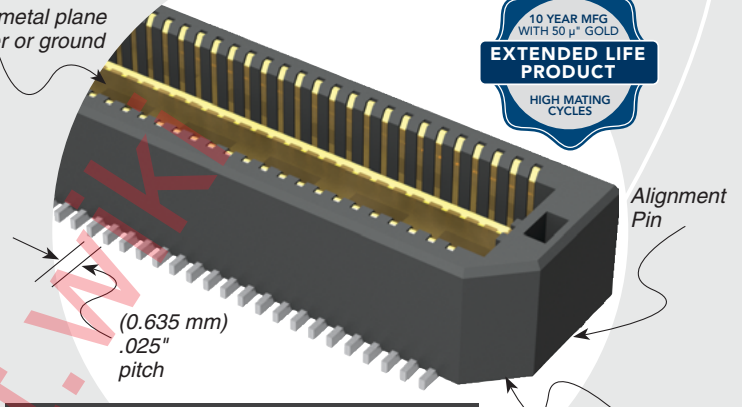
QCDC

**Standoffs:**

SO



Integral metal plane for power or ground



**HIGH-SPEED CHANNEL PERFORMANCE**

QTS/QSS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit [Samtec.com](http://Samtec.com) or contact [SIG@samtec.com](mailto:SIG@samtec.com)

**25**  
G b p s

## PROCESSING

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0.10 mm) .004" max (025-075)

**Board Stacking:**

For applications requiring more than two connectors per board contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)

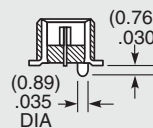
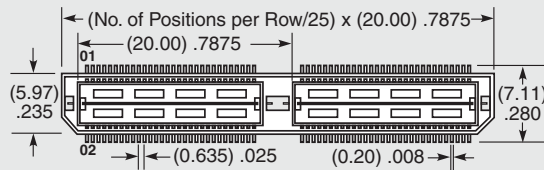


## ALSO AVAILABLE (MOQ Required)

- 11 mm & 16 mm stack height
- 30 μm (0.76 μm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 100 & 125 positions per row
- Edge Mount

**Note:** Some lengths, styles and options are non-standard, non-returnable.

QTS	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
	-025, -050, -075 (50 total positions per bank)	Specify LEAD STYLE from chart.	-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails  -L = 10 μm (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails  -C* = Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, 10 μm (0.25 μm) min Au over 50 μm (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails			-K = (7.00 mm) .275" DIA Polyimide film Pick & Place Pad  -TR = Tape & Reel



\*Note: -C Plating passes 10 year MFG testing

LEAD STYLE	A	MATED HEIGHT
-01	(4.27) .168	(5.00) .197
-02	(7.26) .286	(8.00) .315

Processing conditions will affect mated height. See SO Series for board space tolerances

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.